

CIRCUIT TRACE KEEP OUT AREA
 SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES IN THE LAYOUT SPACE OF THE PRODUCTS.

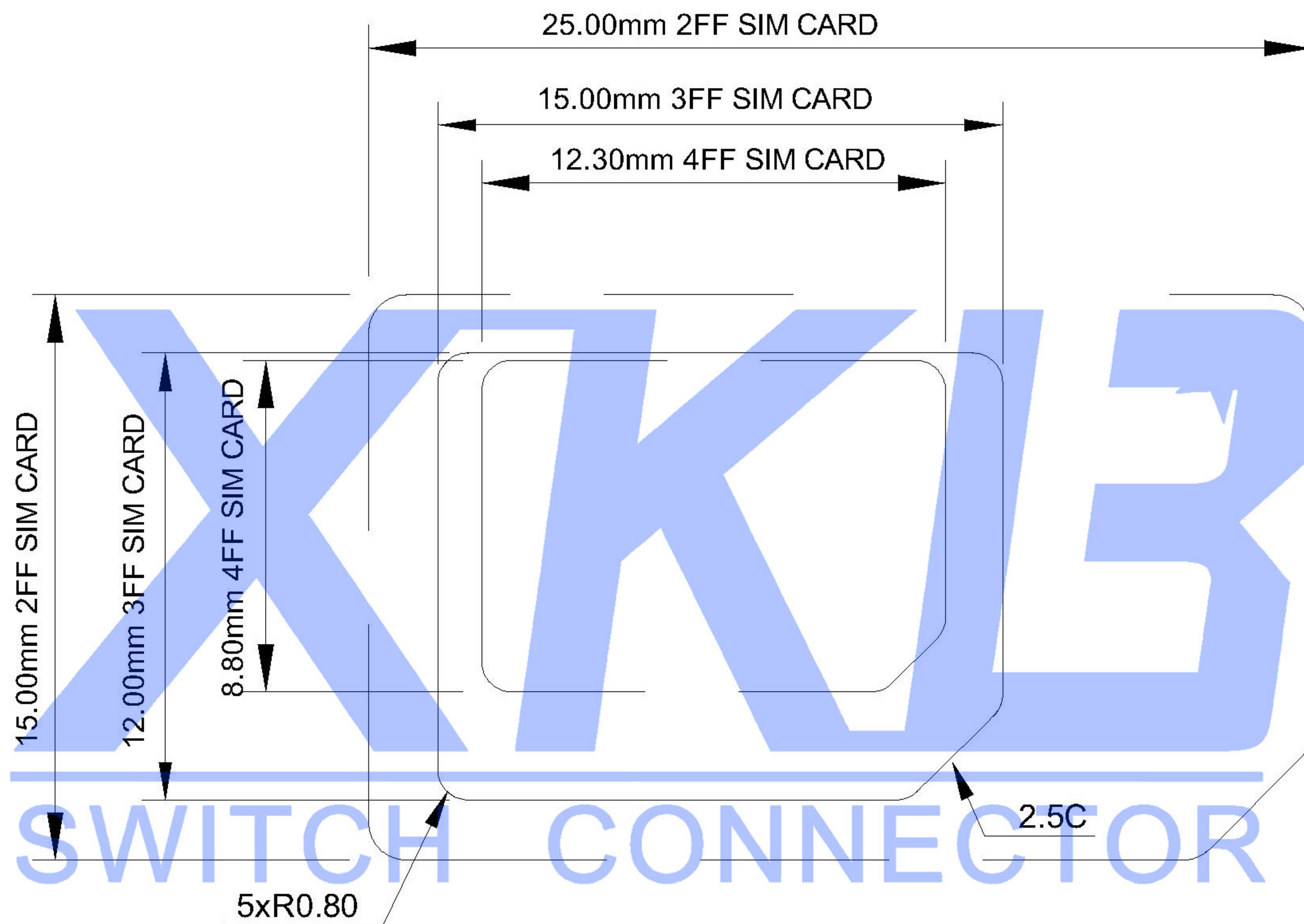
RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ± 0.05

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

PLATING:
 Contact: Plated 30u" Ni Overall ,Solder Area: Tin,Contact G/F
 Shell: Plated 30u" Ni Overall
 Plated G/F Selective Contact Area
Electrical:
 Current Rating :0.5mA max.
 Voltage Rating :50V DC MAX
 Ambient Temperature Range :-20°C~+85°C
 Storage Temperature Range :-40°C~+70°C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100mΩmax.
 Insulation Resistance:1000M min./250V DC
 Dielectric Withstanding Voltage:500V AC
 Mating Cycles:5,000 Insertions
 Temperature : 260°C $\pm 5^\circ$

ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	6	COPPER ALLOY	
①	Housing	1	HI-TEMP.PLASIC UL 94V-0	BLACK

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES	DSND	DATE	SCALE: N/A	MODEL TYPE: SIM CARD CONN		
						DWN	DATE	VIEW:	PART NO.:		
						CHKD	DATE	UNIT: mm	DWG NO.: XKSIM-002-P6		
						APPD	DATE	SIZE: A4	WEIGHT	SHEET	REVISION
Δ X					ANGLAR $\pm 5^\circ$				1.0g	1/1	A0
Δ X					$L \leq 4$ ± 0.2						
Δ X					$4 < L \leq 16$ ± 0.3						
					$16 < L \leq 63$ ± 0.4						
					$L > 63$ ± 0.5						
REVISIONS						XKB INDUSTRIAL PRECISION CO., LIMITED					
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						ANGLAR	±5°	DSND		DATE		SCALE: N/A	MODEL TYPE: SIM CARD CONN
△X						L ≤ 4	±0.2	DWN		DATE		VIEW:	PART NO.:
△X						4 < L ≤ 16	±0.3	CHKD		DATE		UNIT: mm	DWG NO.: XKSIM-002-P6
△X						16 < L ≤ 63	±0.4	APPD		DATE		SIZE: A4	
MARK	DESCRIPTION	DATE	REVISED	APPROVED		L > 63	±0.5						
REVISIONS					UNSPECIFIED TOLERANCES			XKB INDUSTRIAL PRECISION CO., LIMITED			WEIGHT	SHEET	REVISION
www.xk-dg.cn www.helloxkb.com www.helloxkb.cn											1.0g	1/1	A0